

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC61CxxxxxPR-G
Typical Mass: 53 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.246	Silicon	4600	7440-21-3
Leadframe	24.392	Copper	460200	7440-50-8
	0.016	Tin	300	7440-31-5
	0.218	Silver	4100	7440-22-4
Die attach	0.126	Silver	2400	7440-22-4
	0.032	Epoxy	600	—
Bonding wire	0.030	Gold	600	7440-57-5
Resin	23.814	Silica	449300	60676-86-0
	1.943	Epoxy resin	36700	—
	1.402	Phenol resin	26500	—
	0.380	Metal hydroxide	7200	—
Plating	0.400	Tin	7500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."